



ALPHA & OMEGA
SEMICONDUCTOR

AOCA72114

12V Common-Drain Dual N-Channel MOSFET

General Description

- Trench Power MOSFET technology
- Low $R_{SS(ON)}$
- With ESD protection to improve battery performance and safety
- Common drain configuration for design simplicity
- RoHS 2.0 and Halogen-Free Compliant

Applications

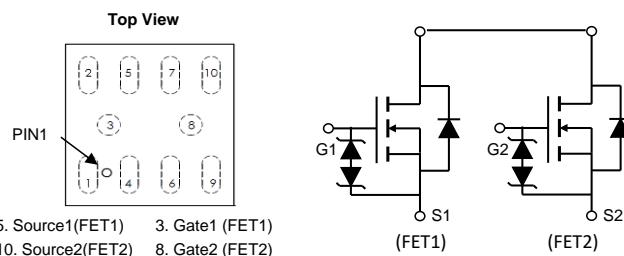
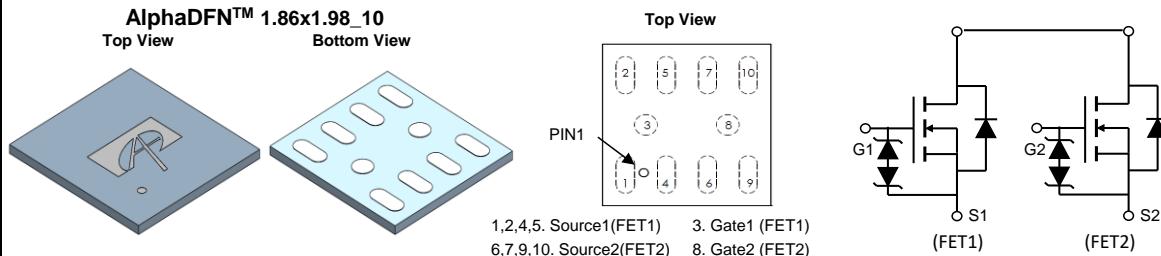
- Battery protection switch
- Mobile device battery charging and discharging

Product Summary

V_{SS}	12V
$R_{SS(ON)}$ (at $V_{GS}=4.5V$)	< 2.7mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.8V$)	< 2.8mΩ
$R_{SS(ON)}$ (at $V_{GS}=3.1V$)	< 3.5mΩ

Typical ESD protection

HBM Class 2



Orderable Part Number	Package Type	Form	Minimum Order Quantity
AOCA72114	AlphaDFN™ 1.86x1.98_10	Tape & Reel	8000

Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Rating	Units
Source-Source Voltage	V_{SS}	12	V
Gate-Source Voltage	V_{GS}	± 8	V
Source Current(DC) ^{Note1}	I_S	24	A
Source Current(Pulse) ^{Note2}	I_{SM}	90	
Power Dissipation ^{Note1}	P_D	2.3	W
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typical	Maximum	Units
Maximum Junction-to-Ambient	$t \leq 10\text{s}$	$R_{θJA}$	35	°C/W
Maximum Junction-to-Ambient	Steady-State		45	°C/W

Note 1. I_S rated value is based on bare silicon. Mounted on 70mmx70mm FR-4 board.

Note 2. PW <10 μs pulses, duty cycle 1% max.

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

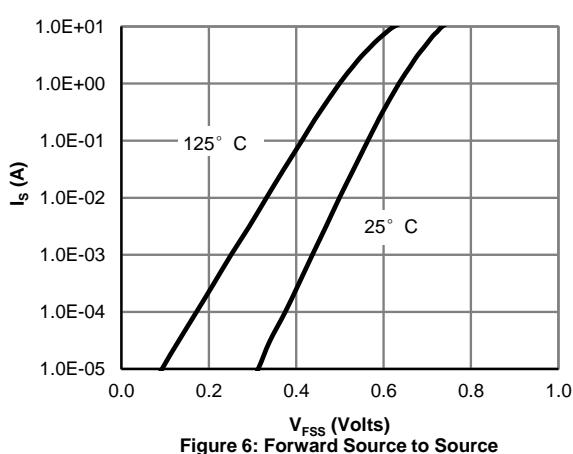
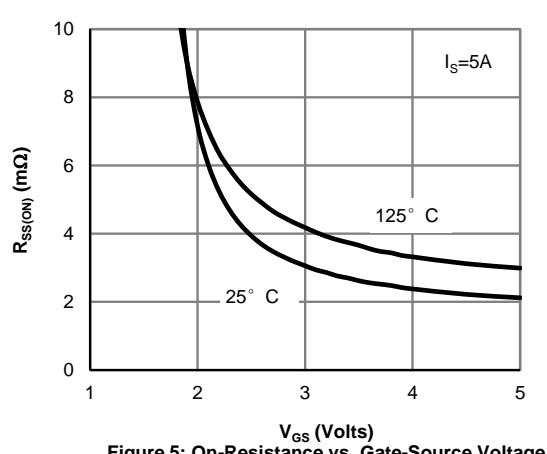
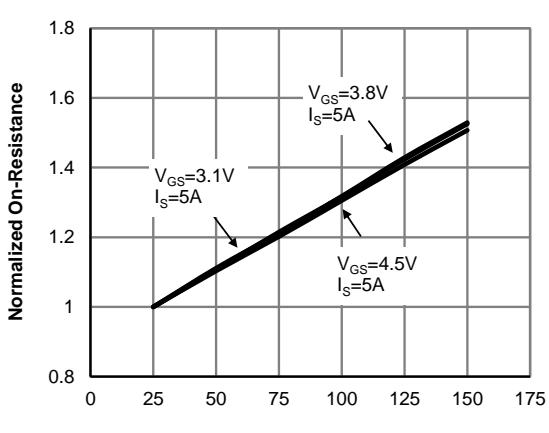
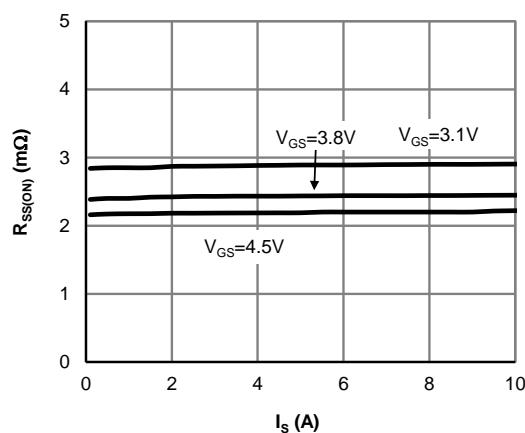
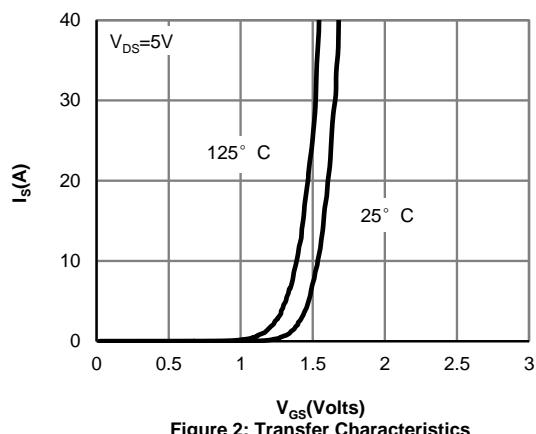
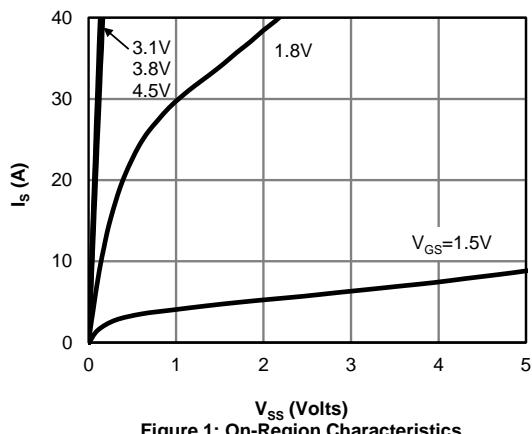
Symbol	Parameter	Conditions	Min	Typ	Max	Units	
STATIC PARAMETERS							
BV_{SSS}	Source-Source Breakdown Voltage	$I_S=250\mu\text{A}, V_{GS}=0\text{V}$	Test Circuit 6	12		V	
I_{SSS}	Zero Gate Voltage Source Current	$V_{SS}=12\text{V}, V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$	Test Circuit 1		1 5	μA	
I_{GSS}	Gate leakage current	$V_{SS}=0\text{V}, V_{GS}=\pm 5\text{V}$	Test Circuit 2		± 1	μA	
		$V_{SS}=0\text{V}, V_{GS}=\pm 8\text{V}$	Test Circuit 2		± 2	μA	
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{SS}=V_{GS}, I_S=250\mu\text{A}$	Test Circuit 3	0.5	0.9	1.3	V
$R_{SS(\text{ON})}$	Static Source to Source On-Resistance	$V_{GS}=4.5\text{V}, I_S=5\text{A}$ $T_J=125^\circ\text{C}$	Test Circuit 4	1.5 2.1	2.2 3.1	2.7 3.8	$\text{m}\Omega$
		$V_{GS}=3.8\text{V}, I_S=5\text{A}$	Test Circuit 4	1.7	2.4	2.8	$\text{m}\Omega$
		$V_{GS}=3.1\text{V}, I_S=5\text{A}$	Test Circuit 4	2	2.85	3.5	$\text{m}\Omega$
g_{FS}	Forward Transconductance	$V_{SS}=5\text{V}, I_S=5\text{A}$	Test Circuit 3		60		S
V_{FSS}	Forward Source to Source Voltage	$I_S=1\text{A}, V_{GS}=0\text{V}$	Test Circuit 5		0.65	1	V
DYNAMIC PARAMETERS							
R_g	Gate resistance	$f=1\text{MHz}$			1.4	$\text{K}\Omega$	
SWITCHING PARAMETERS							
Q_g	Total Gate Charge	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, I_S=5\text{A}$			36	nC	
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{G1S1}=4.5\text{V}, V_{SS}=6\text{V}, R_L=1.2\Omega,$ $R_{\text{GEN}}=3\Omega$	Test Circuit 8		1.8	μs	
t_r	Turn-On Rise Time				6	μs	
$t_{D(\text{off})}$	Turn-Off DelayTime				1.9	μs	
t_f	Turn-Off Fall Time				11	μs	

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS





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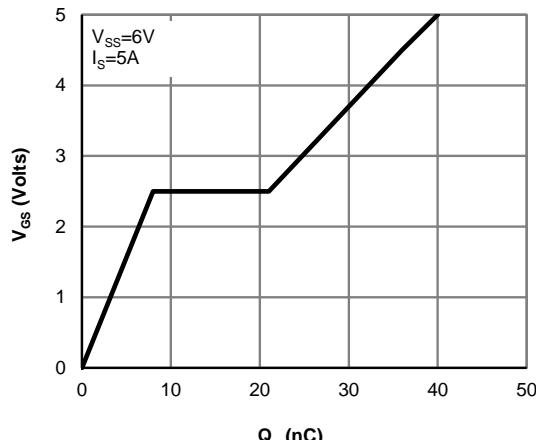


Figure 7: Gate-Charge Characteristics

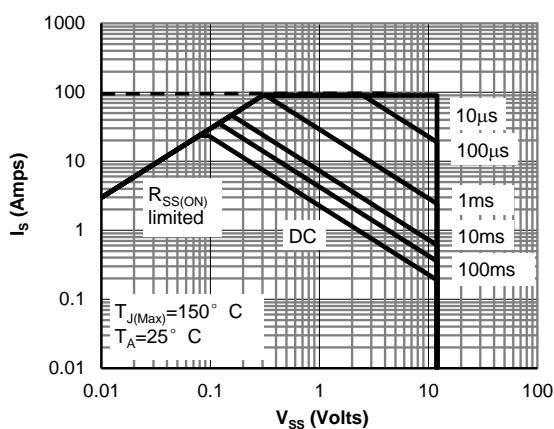


Figure 8: Maximum Forward Biased Safe Operating Area (Note1)

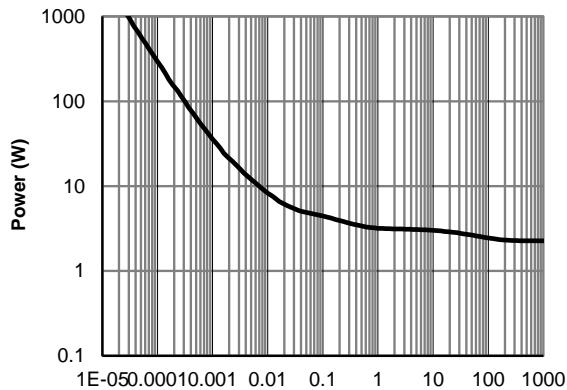


Figure 9: Single Pulse Power Rating Junction-to-Ambient (Note1)

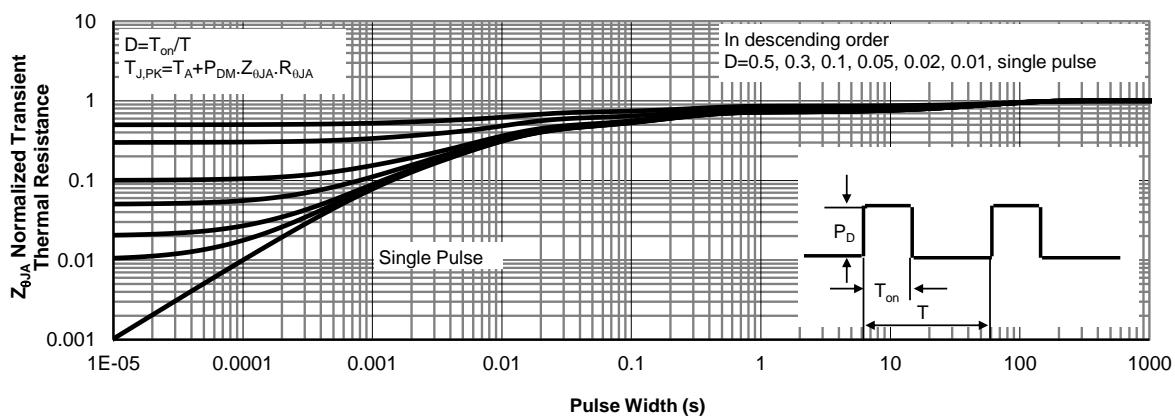
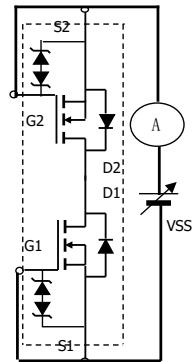


Figure 10: Normalized Maximum Transient Thermal Impedance (Note1)



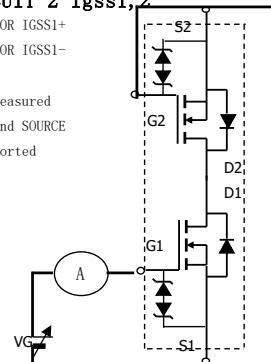
TEST CIRCUIT 1 I_{SSS}

POSITIVE VSS FOR I_{SSS+}
NEGATIVE VSS FOR I_{SSS-}



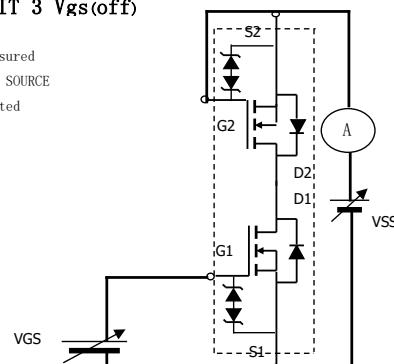
TEST CIRCUIT 2 $I_{gss1,2}$

POSITIVE VGS FOR I_{gss1+}
NEGATIVE VGS FOR I_{gss1-}
When FET1 is measured between GATE and SOURCE of FET2 are shorted



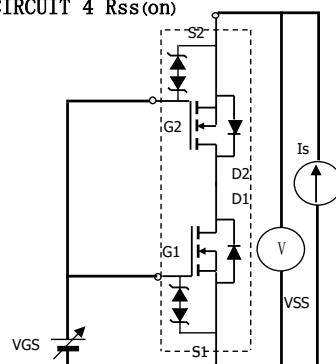
TEST CIRCUIT 3 $V_{gs(off)}$

When FET1 is measured between GATE and SOURCE of FET2 are shorted



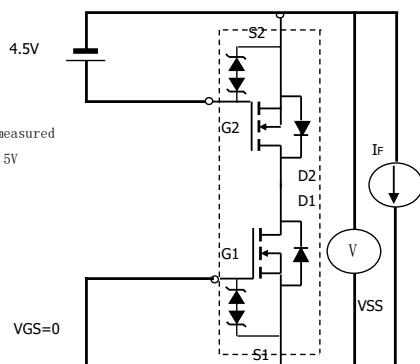
TEST CIRCUIT 4 $R_{ss(on)}$

$V_{ss/Is}$



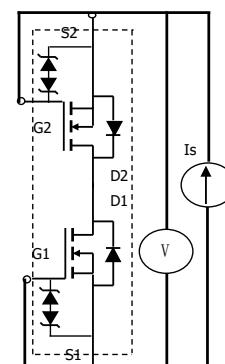
TEST CIRCUIT 5 $V_{F(ss)1,2}$

When FET1 measured
FET2 VGS=4.5V



TEST CIRCUIT 6 BV_{DSS}

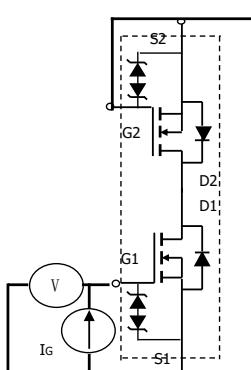
POSITIVE VSS FOR I_{SSS+}
NEGATIVE VSS FOR I_{SSS-}



TEST CIRCUIT 7 $BV_{GS01,2}$

POSITIVE VSS FOR I_{SSS+}
NEGATIVE VSS FOR I_{SSS-}

When FET1 is measured between GATE and SOURCE of FET2 are shorted



**TEST CIRCUIT 8
Switching time**

